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(57)

ABSTRACT

The present disclosure provides an electronic device including a substrate, an extending element, a conductive element and a first insulating layer. The substrate includes an edge. The extending element is disposed on the substrate and includes a first conductive layer and a semiconductor layer, the first conductive layer and the semiconductor layer are overlapped, and the semiconductor layer extends to the edge of the substrate. The conductive element is overlapped with the first conductive layer. The insulating layer is disposed between the conductive element and the extending element.

